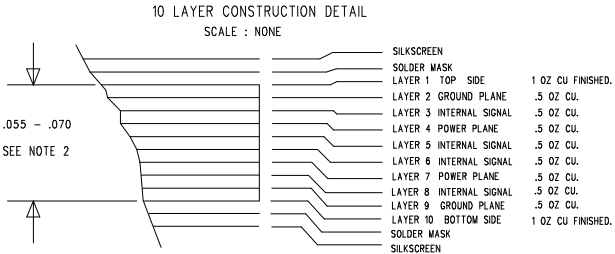
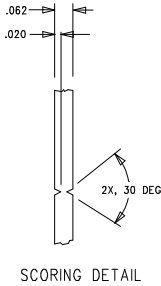
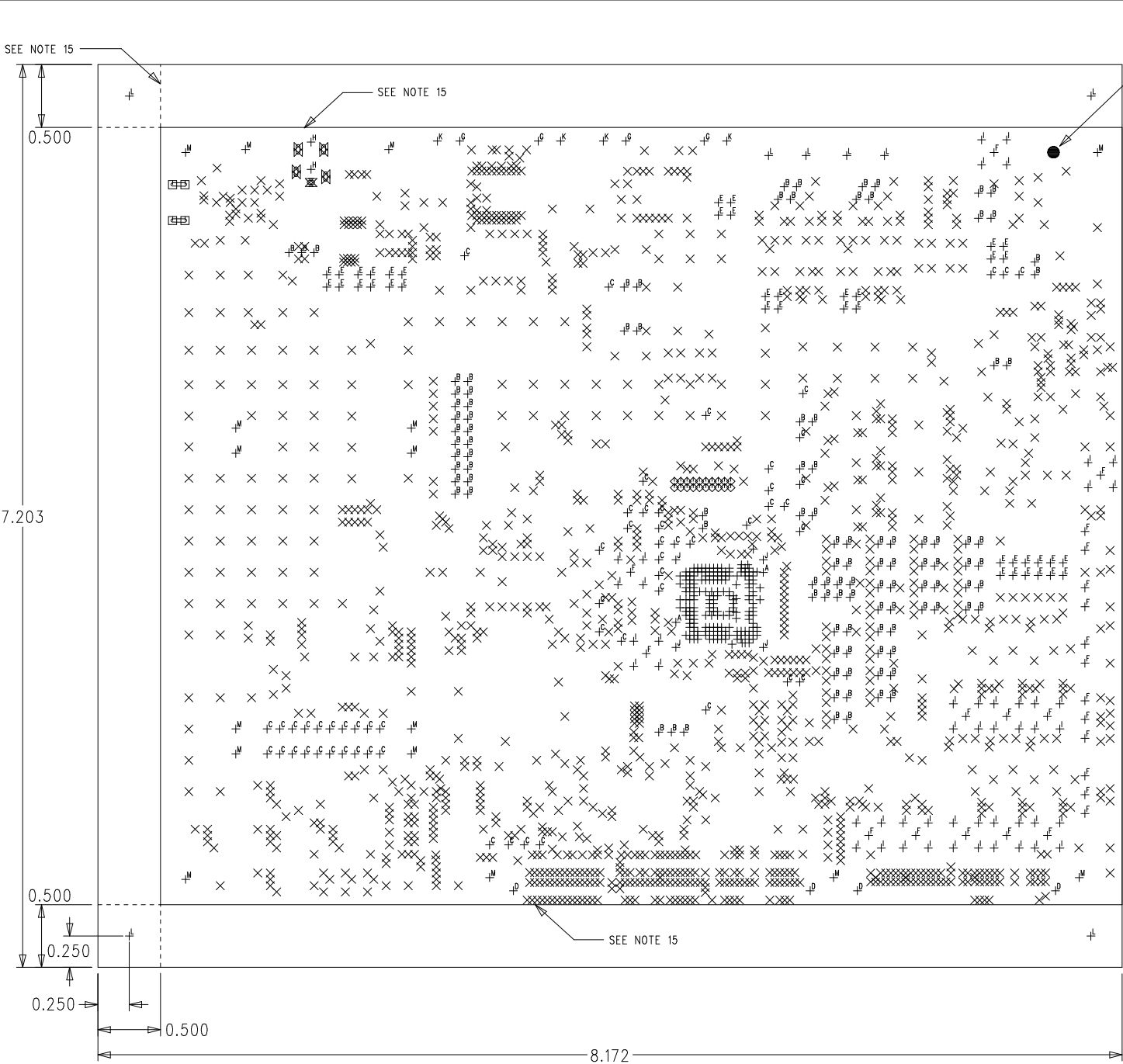


SIZE	QTY	SYM	PLATED	TOL
0.006	195	+	YES	+0.000/-0.006
0.012	1513	X	YES	+/-0.003
0.028 x 0.126	2	□	YES	+/-0.003
0.029	20	◇	YES	+/-0.003
0.032 x 0.06	1	⊗	YES	+/-0.003
0.032 x 0.078	4	⊗	YES	+/-0.003
0.034	2	⊕ ^A	NO	+/-0.003
0.038	108	⊕ ^B	YES	+/-0.003
0.04	58	⊕ ^C	YES	+/-0.003
0.04	4	⊕ ^D	NO	+/-0.003
0.043	40	⊕ ^E	YES	+/-0.003
0.048	24	⊕ ^F	YES	+/-0.003
0.059	4	⊕ ^G	NO	+/-0.003
0.063	2	⊕ ^H	NO	+/-0.003
0.067	48	⊕ ^I	YES	+/-0.003
0.069	4	⊕ ^J	NO	+/-0.003
0.12	4	⊕ ^K	YES	+/-0.005
0.128	8	⊕ ^L	NO	+/-0.005
0.144	16	⊕ ^M	NO	+/-0.005




REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
0.1	NEW RELEASE	C.C.D.	06/15/15	
0.2	UPDATED PER ECO2015-038	C.C.D.	09/23/15	
1.0	UPDATED PER ECO2016-009	C.C.D.	03/16/16	

- UNLESS OTHERWISE SPECIFIED
- BOARD TO BE FABRICATED PER IPC-6012 (LATEST REVISION) CLASS 2.
 - MATERIAL: FR-370HR OR EQUIVALENT, THICKNESS: .062 +/-10%.
VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
 - PLATING: SEE CONSTRUCTION DETAIL FOR FINISHED COPPER WEIGHT.
ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND.
MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE
PER IPC-6012 (LATEST REVISION) WITH AMENDMENT 1, CLASS 2
REQUIREMENTS. WITH NO SINGLE MEASUREMENT LESS THAN 0.00071
IN THE PLATED HOLES.
 - FINISH: SURFACES TO BE COATED BY ENIG OF 3 TO 5 MICROINCHES OVER
A MINIMUM OF 150-200 MICROINCHES OF LOW STRESS NICKEL.
 - SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES
PER GERBER FILES. VENDOR MAY ADJUST SOLDERMASK
PAD SIZE AS NEEDED.
 - SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
 - ARTWORK: MINIMUM FEATURE SIZE = 0.005
MINIMUM AIR GAP = 0.004
 - ALL DIMENSIONS ARE IN INCHES.
 - CONTROLLED IMPEDANCE (+/-10%):
ALL .005" TRACES TO BE 50 OHM SINGLE ENDED. LAYERS 1,3,8,10
ALL .006" TRACES TO BE 50 OHM SINGLE ENDED. LAYERS 5 & 6
ALL .0055" TRACES TO BE 90 OHM DIFFERENTIAL PAIRS.
 - NON-FUNCTIONAL COPPER THIEVING IS ALLOWED ON OPEN AREAS.
 - VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS.
METHOD 1 IS PREFERRED.

METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER
ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK.
AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO
VIA APERTURES BOTH SIDES.

METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/
IMMERSION GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES
THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES.
THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
 - VIA HOLES (.006 & .012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
 - TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
 - USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.
 - V SCORE 3 LINES ON BOTH SIDES OF THE BOARD.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005	CONTRACT NO.		 2 Elizabeth Drive Chelmsford, MA 01824	
	APPROVALS	DATE		
MATERIAL	DRAWN C.C.D.	03/16/16	FABRICATION DRAWING	
SEE NOTES	CHECKED		ADSP-CM419F EZ-KIT	
FINISH	ENGINEERING		SIZE B	REV. 1.0
DO NOT SCALE THIS DRAWING	QUALITY		DWG. NO. A0723-2015	
	MANUFACTURING		SCALE 1 : 1	SHEET 1 OF 1